

*Pre-Amdt-A*  
*10-18-01*  
*Sade*

**PATENT**  
Attorney Docket No. 401263/FUKAMI

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

ABE et al.

Application No.: Unknown

Art Unit: Unknown

Filed: June 28, 2001

Examiner: Unknown

For: SEMICONDUCTOR  
DEVICE AND  
MANUFACTURING  
METHOD THEREOF

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Prior to the examination of the above-identified patent application, please enter the following amendments and consider the following remarks.

IN THE DRAWINGS:

The Examiner is requested to approve the changes to Figures 9-21 and 29-35 as indicated in the attached Request for Approval of Drawing Amendments.

IN THE SPECIFICATION:

Replace the paragraph beginning at page 2, line 1 with:

Through never-ending progress in downsizing of semiconductor chips, a semiconductor chip is now almost thinner than a lead frame. Such semiconductor chips have become highly dense, while densification of a semiconductor device mounting these semiconductor chips is insufficient. In particular, current semiconductor devices are not thin enough as thinning thereof has rarely received attention. Then, with a rapid

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*cont*